

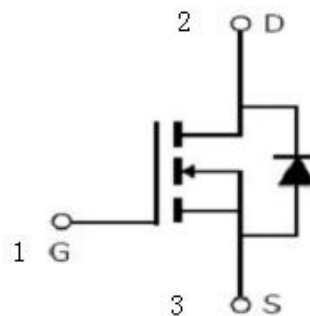
General Description

These N-Channel enhancement mode power field effect transistors are using trench DMOS technology. This advanced technology has been especially tailored to minimize on-state resistance, provide superior switching performance, and withstand high energy pulse in the avalanche and commutation mode. These devices are well suited for high efficiency fast switching applications.

Features

V_{DS}	40V
I_D (at $V_{GS}=10V$)	90A
$R_{DS(ON)}$ (at $V_{GS}=10V$)	4.2m Ω (Typ)

PDFN5*6



Absolute Maximum Ratings $T_A=25^\circ\text{C}$ unless otherwise noted

Parameter	Symbol	Maximum	Units	
Drain-Source Voltage	V_{DS}	40	V	
Gate-Source Voltage	V_{GS}	± 20	V	
Drain Current-Continuous	TC=25 $^\circ\text{C}$	I_D	90	A
	TC=100 $^\circ\text{C}$	I_D	57	A
Maximum Power Dissipation	P_D	83	W	
Junction and Storage Temperature Range	T_J, T_{STG}	-55 To 150	$^\circ\text{C}$	

Thermal Characteristics

Parameter	Symbol	Typ	Max	Unit
Thermal Resistance junction-case	$R_{\theta Jc}$		1.1	$^\circ\text{C/W}$
Thermal Resistance junction-to-Ambient	$R_{\theta JA}$		62	$^\circ\text{C/W}$

Electrical Characteristics (T_J=25°C unless otherwise noted)

Symbol	Parameter	Condition	Min	Typ	Max	Unit
STATIC PARAMETERS						
BV_{DSS}	Drain-Source Breakdown Voltage	$V_{GS}=0V, I_D=250\mu A$	40			V
I_{DSS}	Zero Gate Voltage Drain Current	$V_{DS}=40V, V_{GS}=0V$			1	μA
I_{GSS}	Gate-Body Leakage Current	$V_{GS}=\pm 20V, V_{DS}=0V$			± 100	nA
$V_{GS(th)}$	Gate Threshold Voltage	$V_{DS}=V_{GS}, I_D=250\mu A$	1.0	1.6	2.5	V
$R_{DS(on)}$	Drain-Source On-State Resistance	$V_{GS}=10V, I_D=20A$		4.2	5.2	m Ω
		$V_{GS}=4.5V, I_D=10A$		5.3	7.0	m Ω
DYNAMIC PARAMETERS						
C_{ISS}	Input Capacitance	$V_{DS}=25V, V_{GS}=0V,$ $F=1.0MHz$		2400		pF
C_{OSS}	Output Capacitance			230		pF
C_{RSS}	Reverse Transfer Capacitance			150		pF
SWITCHING PARAMETERS						
$t_{d(on)}$	Turn-on Delay Time	$V_{DD}=20V, I_D=1A,$ $V_{GS}=10V,$ $R_G=3.3\Omega$		14		nS
t_r	Turn-on Rise Time			18		nS
$t_{d(off)}$	Turn-Off Delay Time			38		nS
t_f	Turn-Off Fall Time			14		nS
Q_g	Total Gate Charge	$V_{DS}=30V, I_D=10A,$ $V_{GS}=4.5V$		25		nC
Q_{gs}	Gate-Source Charge			6.5		nC
Q_{gd}	Gate-Drain Charge			12		nC
V_{SD}	Diode Forward Voltage (2)	$V_{GS}=0V, I_{SD}=1A$		0.72	1.3	V
R_g	Gate resistance	$V_{GS}=0V, V_{DS}=0V,$ $F=1MHz$		1.6		Ω

Note:

1. Repetitive Rating : Pulsed width limited by maximum junction temperature.
2. The data tested by pulsed , pulse width $\leq 300\mu s$, duty cycle $\leq 2\%$.
3. Essentially independent of operating temperature.

TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS

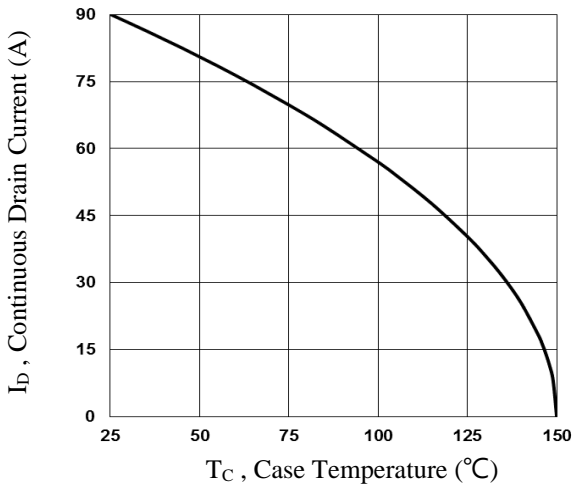


Fig.1 Continuous Drain Current vs. T_c

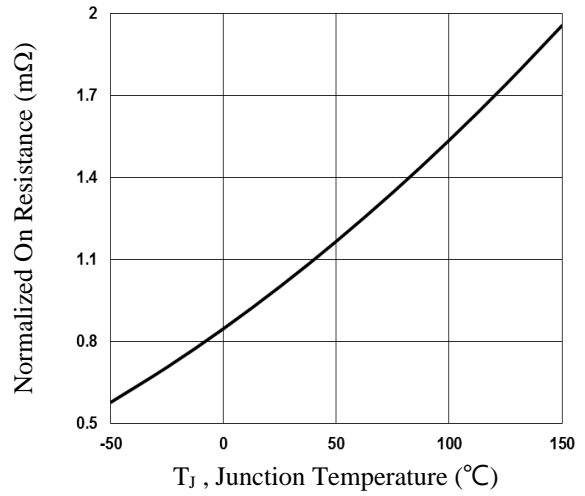


Fig.2 Normalized $R_{DS(on)}$ vs. T_j

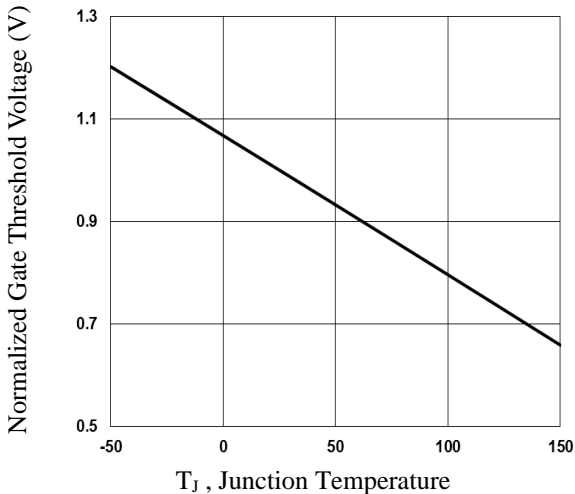


Fig.3 Normalized V_{th} vs. T_j

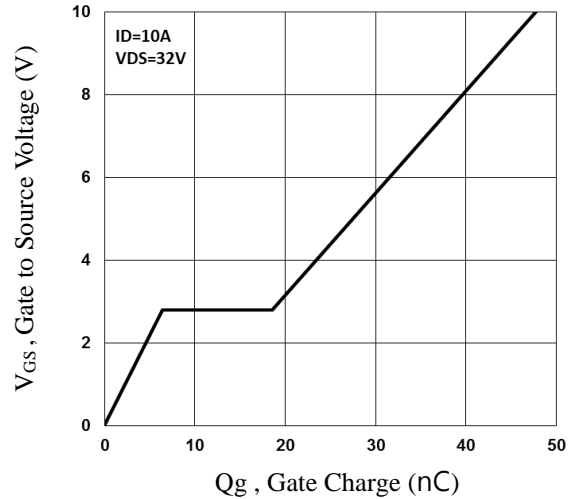


Fig.4 Gate Charge Waveform

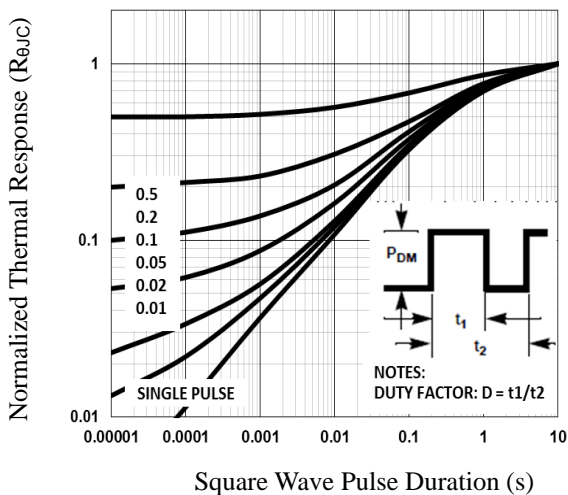


Fig.5 Normalized Transient Impedance

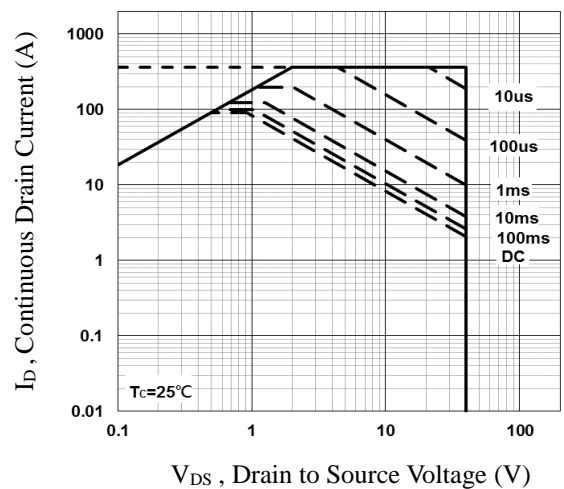


Fig.6 Maximum Safe Operation Area

TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS

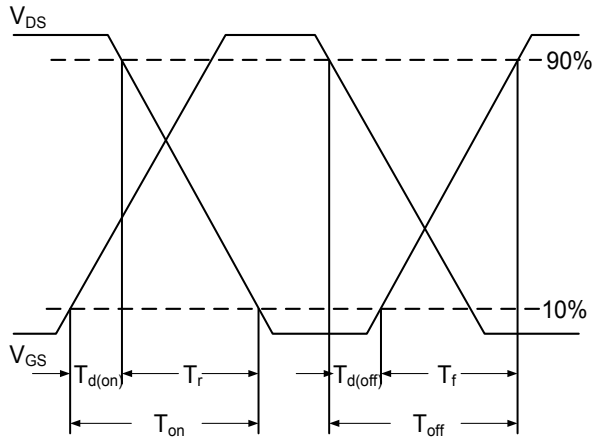


Fig.7 Switching Time Waveform

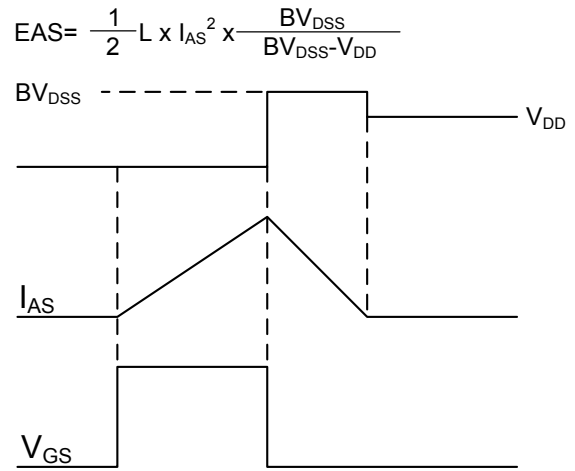
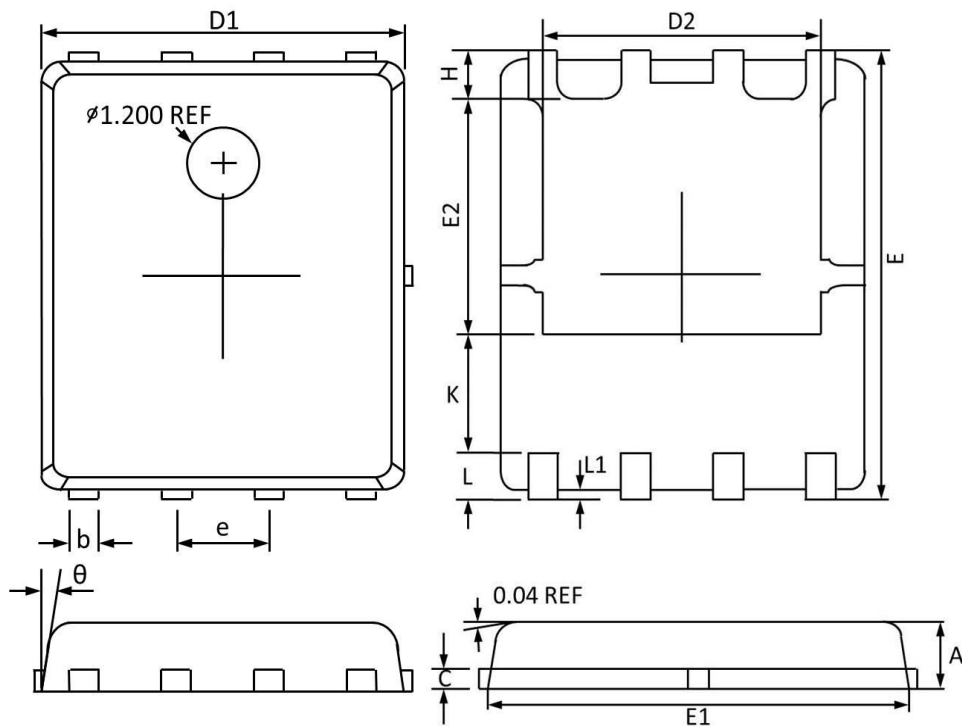


Fig.8 EAS Waveform

PDFN5X6 PACKAGE INFORMATION



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	MAX	MIN	MAX	MIN
A	1.100	0.800	0.043	0.031
b	0.510	0.330	0.020	0.013
C	0.300	0.200	0.012	0.008
D1	5.100	4.800	0.201	0.189
D2	4.100	3.610	0.161	0.142
E	6.200	5.900	0.244	0.232
E1	5.900	5.700	0.232	0.224
E2	3.780	3.350	0.149	0.132
e	1.27BSC		0.05BSC	
H	0.700	0.410	0.028	0.016
K	1.500	1.100	0.059	0.043
L	0.710	0.510	0.028	0.020
L1	0.200	0.060	0.008	0.002
θ	12°	0°	12°	0°